

DE LA RECHERCHE À L'INDUSTRIE





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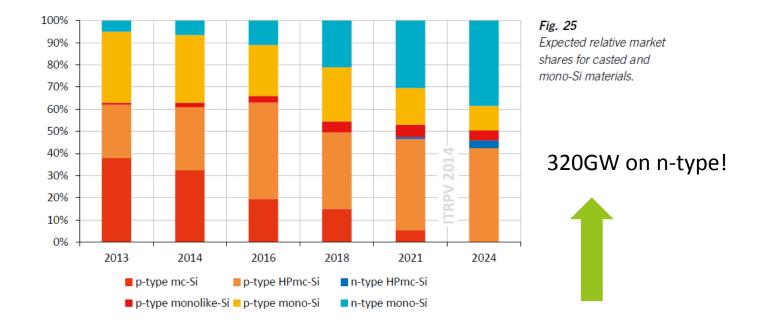
SILICON (REAR CONTACT)



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ceatech introduction



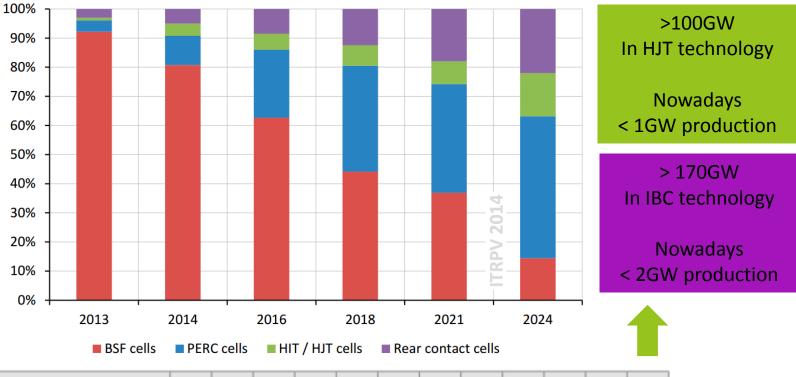


	06/ 2012	12/ 2012			12/ 2015	12/ 2016		12/ 2018	12/ 2020	12/ 2021	12/ 2023	12/ 2024
Cum. volume shipped (GW)	92	110	150	200	260	320	380	440	560	630	770	850

HERCULES n-type material







	06/ 2012	12/ 2012	12/ 2013		12/ 2015	12/ 2016			12/ 2020	12/ 2021	12/ 2023	12/ 2024
Cum. volume shipped (GW)	92	110	150	200	260	320	380	440	560	630	770	850

HJT in the HERCULES project

IBC in the HERCULES project





Heterojunction history vs standard solar cells

HJT vs diffused cells

Process flow: what is different?

Challenges of heterojunctions solar cells

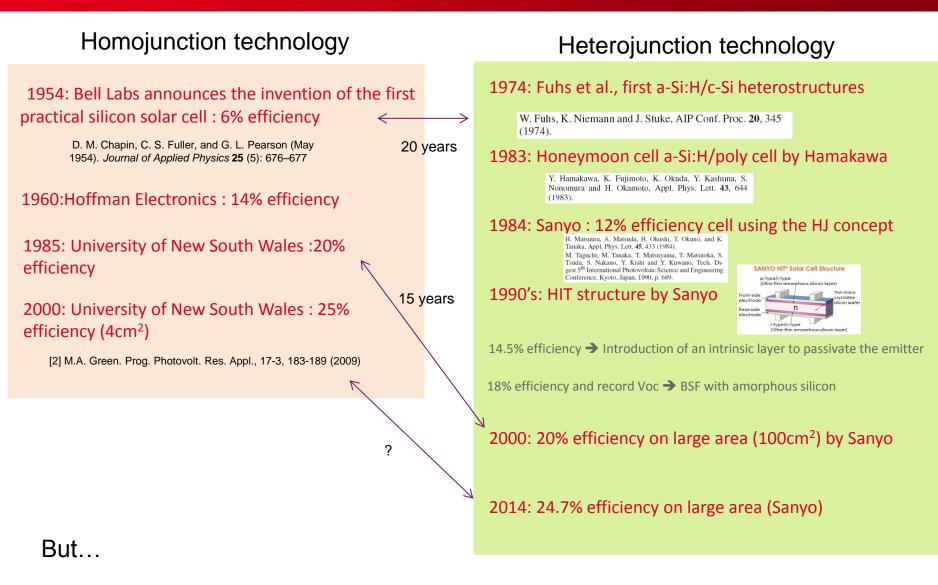
...and diffused cells

Costs?

Towards HET-IBC: does it makes sense?

ceatech A BIT OF HISTORY



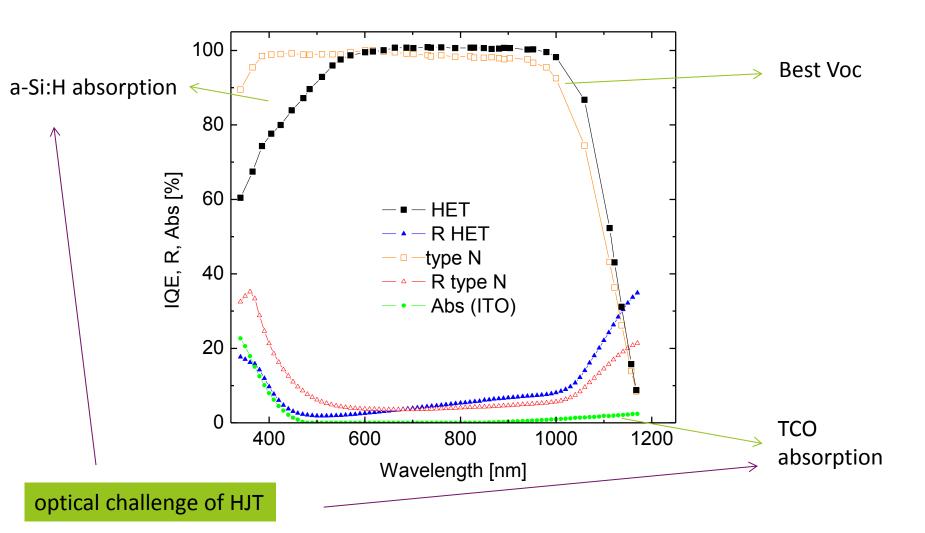


2014: Sunpower 25% IBC vs Panasonic IBC-HET 25.7%





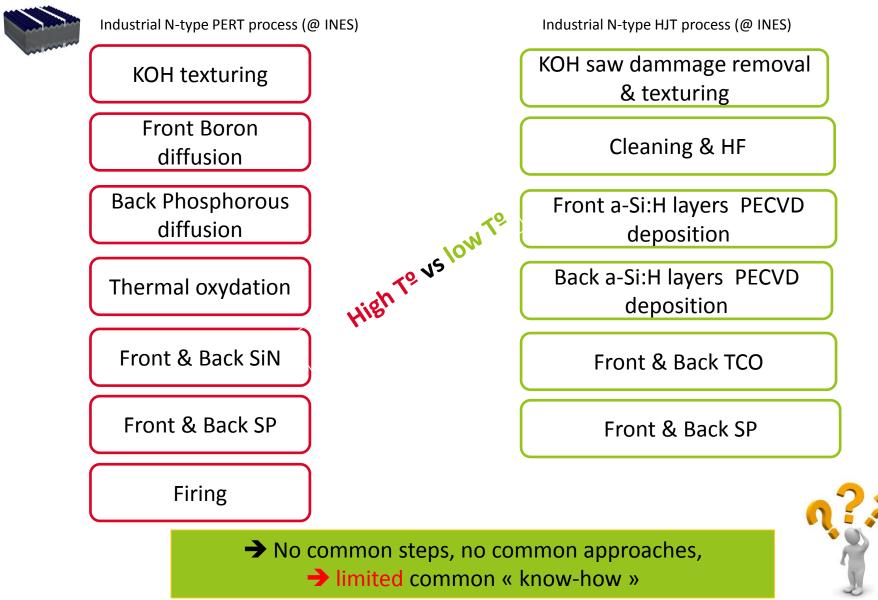
HJT : High Voc vs difussed cells: High Jsc



Ceatech HJT VS DIFFUSSED CELLS





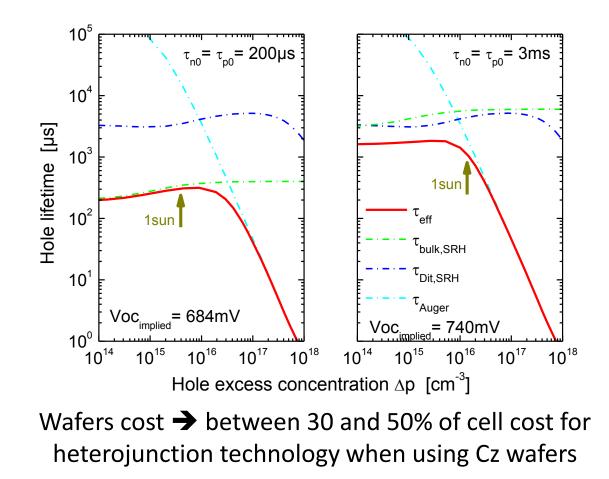






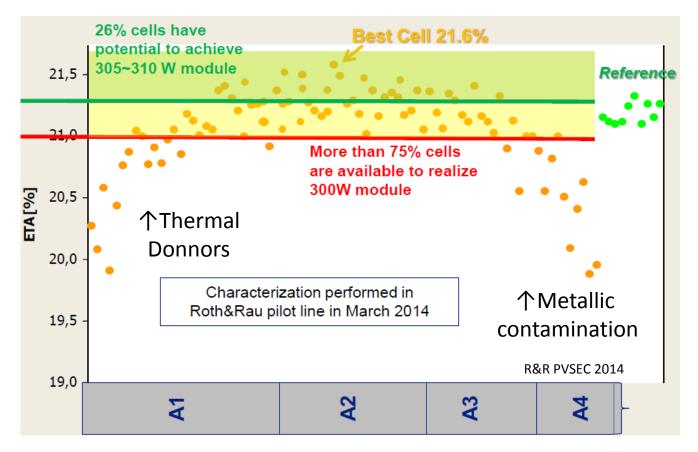
Material criticity for high Voc

Need of very high quality materials (τ_{bulk} >3ms)





Material criticity for high Voc AND lower costs





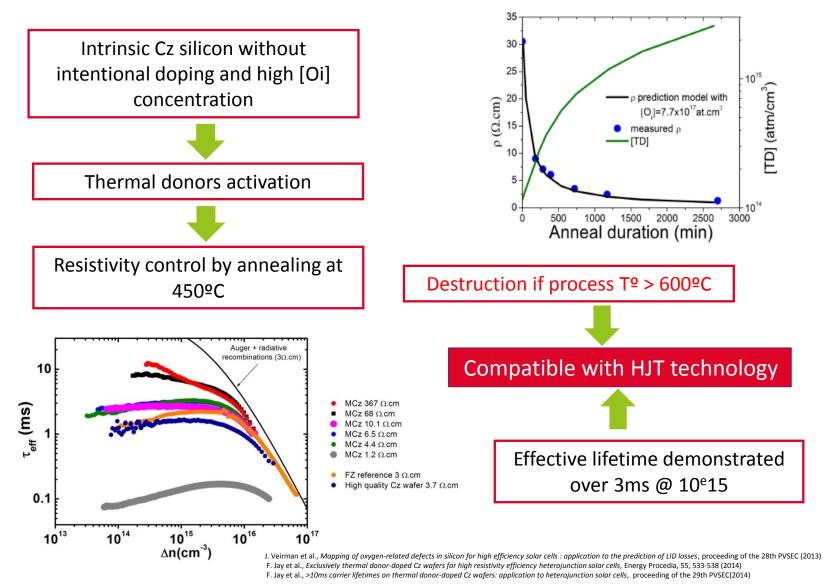
Improve ingot use up to 100%

thermal donnors doping?

Ceatech CHALLENGES FOR HJT TECHNOLOGY



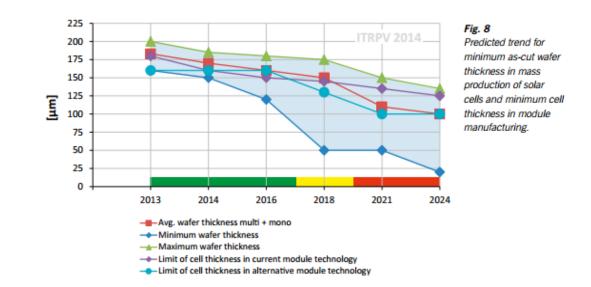
Strategy for n-type ingot doped with thermal donnors





Material criticity for high Voc AND lower costs

Use of thin wafers compatible with low temperature processes (improve Voc)



→Integration on process manufacturing

→ Absorption improvement in the IR region

Possibility of double cost reductions (€/W)

Ceatech CHALLENGES OF HJT



Material criticity: Silver consumption in screen-printing pastes for high efficiencies

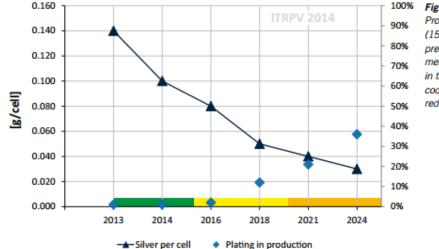


Fig. 9
Proportion of silver per cell
(156x156 mm²) and the
predicted share of different
metallization technologies
in the cell process. (Color
coding refers to silver
reduction).

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technology		mg Ag /cell
standard HJT cells	front side	110
	bifacial	300
smart-wire HJT cells	front side	20
	bifacial	50
standard diffused cells	front side	90
standard diffused cells	bifacial	180
smart-wire diffused cells	front side	30
Smart-wire dilfused cells	bifacial	30

Big challenge for HJT technology to reduce silver consumption in the next years to be cost competitive specially bifacial cells

- → Integration of SW technology
- → Patterning + Cu plating

85% Ag content in the paste Source: INES



- 1. High temperature steps on material:
 - ➔ Oi behavior?
 - ➔ compatibility with thin wafers?
 - ➔ equipment contamination?
- 2. How to reach high Voc?
- a/ Lowly doped regions
- \rightarrow Compatibility of screen-printing with low-doping profiles?
- b/ recombination at metal/SC interface (J0met)
- → Plating?
- ➔ passivated contacts?
- ➔ New generation of pastes

If high Voc: same constraints as HJT for silicon material (high lifetime>3ms!)

- 3. And decrease Silver consumption, of course!
- ightarrow Less limited than HTJ



Both technologies deal with:

- Improvement on series resistance
- Improvement on pFF: edge isolation
- Production issues impacting FF (handling, wet treatments...)

&

- Continuous cost reduction
- Reliability: no LID, no degradation

ROM RESEARCH TO INDUSTRY

<u>ceatech</u> costs? INCLUDING CAPEX OR NOT?



	Diffused cells	HJT cells
material	 (not forget mc-Si& ML compatibility) 	++
process	+	+
Metallization Ag	++	+++
Smart-wire	+	+
Cu plating	++	+
Module monofacial	PERT +	+
Module bifacial	PERC +	+

- Process HTJ cells costs are similar to n-type diffused cells except for material quality & standard BB metallization
- SW & Plating are good reduction cost vectors for HJT technology
- Bifacial module integration is a joker for both technologies

Production costs (CaPex, Opex) are driven by production capacity

<u>ceatech</u> towards het-IBC: DOES IT MAKES SENSE?



World record silicon solar cells > 25% efficiency

	J _{SC} (mA/cm²)	V _{oc} (mV)	FF (%)	Rdt (%)
PANASONIC (IBC HET 143 cm ²)	41,8	740	82,7	25,6
SHARP (IBC HET 4 cm ²)	41,7	736	81,9	25,1
Sunpower (IBC 121 cm ²)	41,2	730	83	25,0

At the cell level: better short-circuit current & Voc than diffussed junction **FF comparable to diffused junctions**

Challenges:

- → patterning of a-Si:H layers / TCO / metallization with industrial techniques
- → Full wafer/large area integration
- → what about costs? Will €/W & €/KWh be reasonnable?
- ➔ Too many steps, big impact on costs (both CaPEX → investments and OPEX→ wafer breakage, material)





- N-type diffused cells and heterojunctions are promising technologies but some challenges still need to be solved (the HERCULES project addresses some of them!)
- HJT vs diffused cells: No common process steps, no industrial compatibility
- HJT cells performance and cost strongly depend on material quality. TD technology can be an innovating option to assure high performances lowering costs.
- Diffused cells deals with improvements on Voc to reach higher efficiencies.
- Both technologies deal with production issues in Europe (HERCULES!)





Thanks to Yannick (n-type diffused team!) & Pierre-Jean for their help! Thanks to all the LHET team

Thank you for your attention!



Picture of the French National Institute for Solar Energy (INES)